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SSISTANT COMMISSIONER FOR PATENTS Vashington, D.C. 20231

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s): Tadashi KOMIYAMA, Akitoshi HARA, and Eiichi SATO

For: METHODS FOR MANUFACTURING SEMICONDUCTOR CHIPS, METHODS FOR

MANUFACTURING SEMICONDUCTOR DEVICES, SEMICONDUCTOR CHIPS, SEMICONDUCTOR DEVICES, CONNECTION SUBSTRATES AND ELECTRONIC DEVICES

Enclosed are:

X	20 Pages of text and <u>6</u> Sheet(s) of drawings (<u>X</u> formal <u>informal</u>) + <u>0</u> extra copies
	A certified copy of 2000-28366, filed 4 Feb. 2000, in Japan, and 2001-14025, filed 23 Jan. 2001, in Japan
	from which priority is claimed in the subject case pursuant to Rule 55(b) and 35 USC 119. X Will follow.
	Declaration and Power of Attorney. X Will Follow.

CALCULATION OF FEES							
ITEM		NUMBER OF CLAIMS FILED MINUS BASE*	NUMBER OF CLAIMS OVER BASE x RATE SM/LG ENTITY	\$ AMOUNT	\$ FEE		
A	TOTAL CLAIMS FEE	23 - 20* =	x \$9.00 or 3 x \$18.00	\$54			
В	INDEPENDENT CLAIMS FEE**	7 - 3*=	x \$40.00 or 4 x \$80.00	\$320			
С	SUBTOTAL - ADDITIONAL CLAIMS FEE (ADD FINAL COLUMN IN LINES A + B)						
D	BASIC FEE – SMALL ENTITY FEE = \$355.00 / LARGE ENTITY FEE = \$710						
Е	MULTIPLE-DEPENDENT CLAIMS FEE – SMALL ENTITY FEE = \$130.00 /LARGE ENTITY FEE = \$260				\$0		
F	ASSIGNMENT RECORDING FEE \$ 40.00				\$0		
G	TOTAL FEE (ADD LINES C, D, E AND F)						
	**LIST INDEPENDENT CLAIMS 1, 4, 6, 9, 11, 17, 22						

- X A check in the amount of \$1084.00 to cover the filing fee is enclosed. A copy of this letter is enclosed.
- X The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0585. A duplicate copy of this sheet is enclosed.
 - X Any additional filing fees required under 37 CFR 1.16.
 - X Any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

Date: February <u>4</u>, 2001

Alan S. Raynes, Reg. No. 39,809

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Customer No. 24033

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

	ne Application of YAMA et al.	
Serial 1	No.: To Be Assigned	
Filing	Date:	ノンソン
For:	METHODS FOR MANUFACTURING SEMICONDUCTOR CHIPS, METHODS FOR MANUFACTURING SEMICONDUCTOR DEVICES, SEMICONDUCTOR CHIPS, SEMICONDUCTOR DEVICES, CONNECTION SUBSTRATES AND ELECTRONIC DEVICES	

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Assistant Commissioner for Patents Washington, DC 20231

Express Mail Label No.: EL 273 653 750 US Date of Deposit: February <u>4</u>, 2001

I hereby certify that a utility patent application and patent application fee transmittal; patent application including 20 pages of text (including an abstract and 23 claims), 6 sheets of drawings; a \$1084 check for the filing fee; and a return postcard are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Box Patent Application, Washington, DC 20231.

Date of Deposit

Alan S. Raynes

Name of person mailing papers

Signature